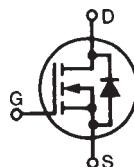


PolarHV™ HiPerFET Power MOSFET

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode

IXFH 36N60P
IXFK 36N60P
IXFT 36N60P

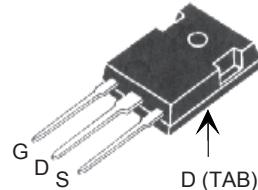
$V_{DSS} = 600$ V
 $I_{D25} = 36$ A
 $R_{DS(on)} \leq 190$ mΩ
 $t_{rr} \leq 200$ ns



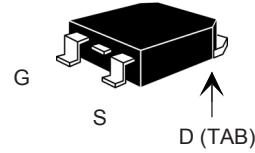
Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	600	V
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$; $R_{GS} = 1 M\Omega$	600	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	$T_c = 25^\circ C$	36	A
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	80	A
I_{AR}	$T_c = 25^\circ C$	36	A
E_{AR}	$T_c = 25^\circ C$	50	mJ
E_{AS}	$T_c = 25^\circ C$	1.5	J
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100$ A/ μ s, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$, $R_G = 4 \Omega$	20	V/ns
P_D	$T_c = 25^\circ C$	650	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
M_d	Mounting torque (TO-247 & TO-264)	$1.13/10$ Nm/lb.in.	
Weight	TO-247	6	g
	TO-268	5	g
	TO-264	10	g
T_L	1.6 mm (0.062 in.) from case for 10 s	300	$^\circ C$
T_{SOLD}	Plastic body for 10 s	260	$^\circ C$

Symbol	Test Conditions	Characteristic Values		
	($T_J = 25^\circ C$, unless otherwise specified)	Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0$ V, $I_D = 250$ μ A	600		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4$ mA	3.0		V
I_{GSS}	$V_{GS} = \pm 30$ V _{DC} , $V_{DS} = 0$		± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0$ V	$T_J = 125^\circ C$	100	μ A
			1000	μ A
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300$ μ s, duty cycle $d \leq 2$ %		190	mΩ

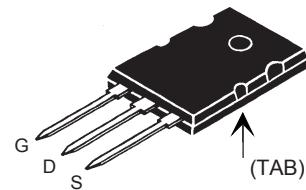
TO-247 (IXFH)



TO-268 (IXFT) Case Style



TO-264 AA (IXFK)



G = Gate D = Drain
S = Source Tab = Drain

Features

- International standard packages
- Fast recovery diode
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

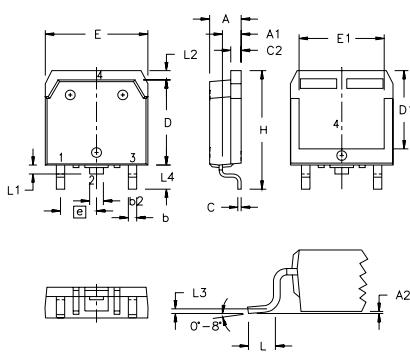
Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ C$, unless otherwise specified)	Min.	Typ.
g_{fs}	$V_{DS} = 20 V$; $I_D = 0.5 I_{D25}$, pulse test	25	39	S
C_{iss}		5800		pF
C_{oss}		570		pF
C_{rss}		30		pF
$t_{d(on)}$		30		ns
t_r		25		ns
$t_{d(off)}$		80		ns
t_f		22		ns
$Q_{g(on)}$		102		nC
Q_{gs}		34		nC
Q_{gd}		36		nC
R_{thJC}			0.19	$^\circ C/W$
R_{thCS}	TO-247	0.21		$^\circ C/W$
R_{thCS}	TO-264	0.15		$^\circ C/W$

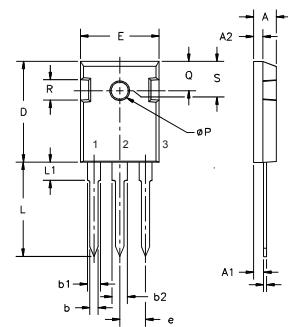
Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ C$, unless otherwise specified)	Min.	Typ.
I_s	$V_{GS} = 0 V$		36	A
I_{SM}	Repetitive		80	A
V_{SD}	$I_F = I_s$, $V_{GS} = 0 V$, Pulse test, $t \leq 300 \mu s$, duty cycle $d \leq 2\%$		1.5	V
t_{rr}	$I_F = 25 A$, $-di/dt = 100 A/\mu s$		200	ns
Q_{RM}	$V_R = 100 V$	0.8		μC
I_{RM}		6.0		A

TO-268 (IXFT) Outline



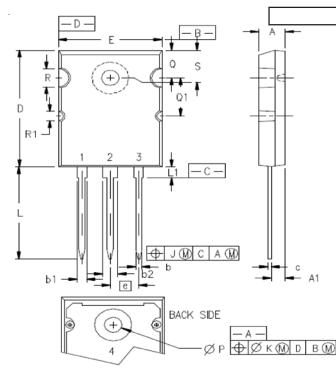
SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

TO-247 AD (IXFH) Outline



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	.205	.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	.232	.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

TO-264 (IXFK) Outline



1 - GATE
2, 4 - DRAIN (COLLECTOR)
3 - SOURCE (EMITTER)

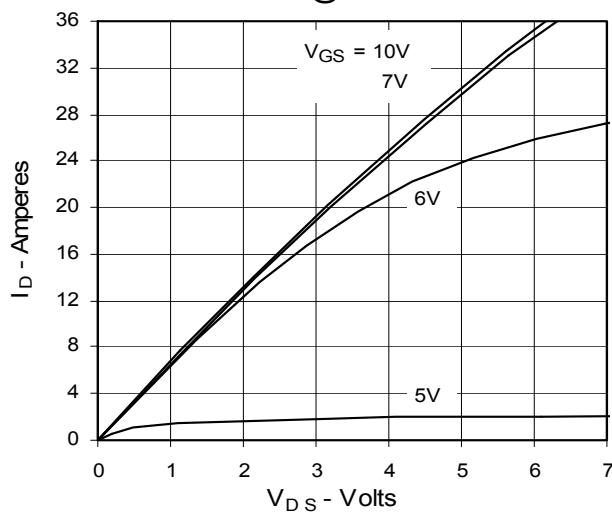
SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215BSC		5.46 BSC	
J	.000	.010	0.00	0.25
K	.000	.010	0.00	0.25
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
ØP	.122	.138	3.10	3.51
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR1	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36
S	.243	.253	6.17	6.43

IXYS reserves the right to change limits, test conditions, and dimensions.

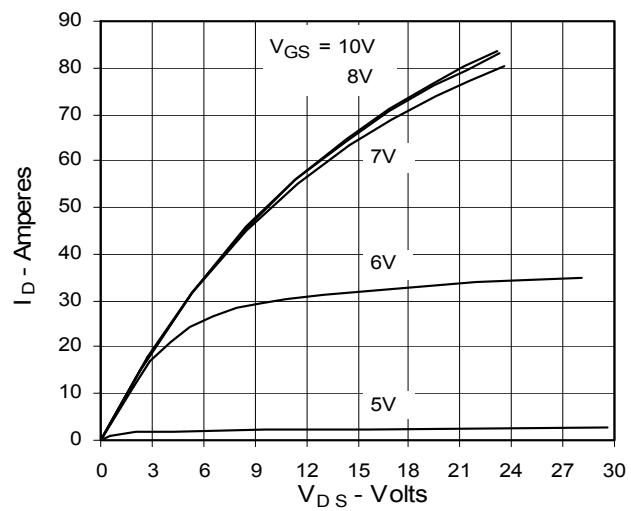
IXYS MOSFETs and IGBTs are covered by 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 one or more of the following U.S. patents: 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505

6,710,405B2 6,759,692 6,710,463 6,771,478 B2

**Fig. 1. Output Characteristics
@ 25°C**



**Fig. 2. Extended Output Characteristics
@ 25°C**



**Fig. 3. Output Characteristics
@ 125°C**

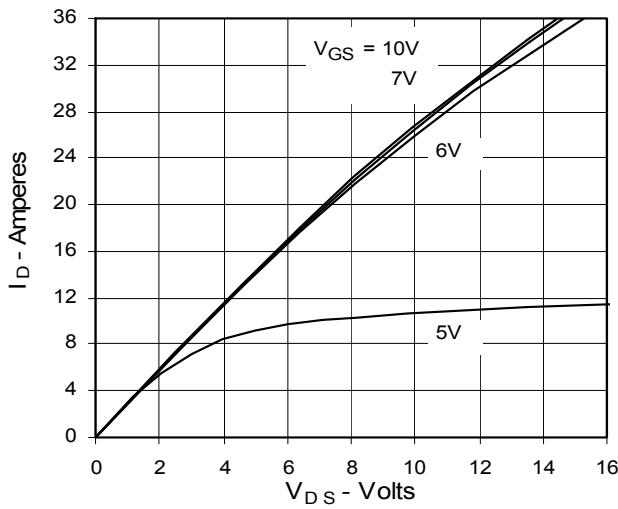
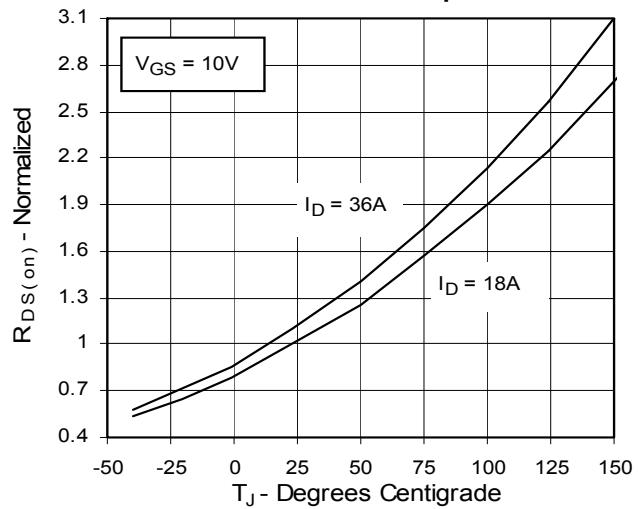


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature



**Fig. 5. $R_{DS(on)}$ Normalized to
0.5 I_{D25} Value vs. I_D**

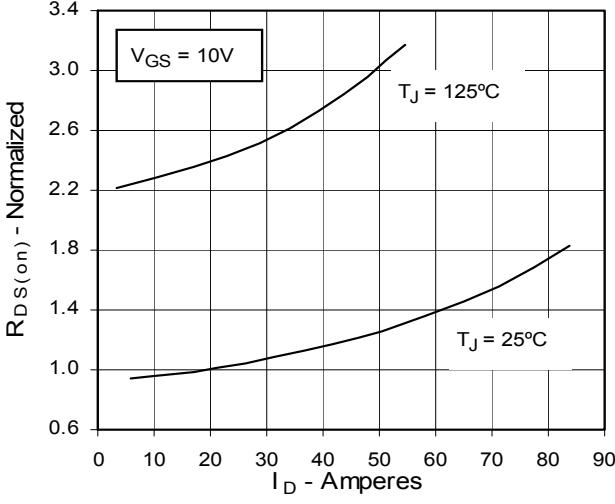


Fig. 6. Drain Current vs. Case Temperature

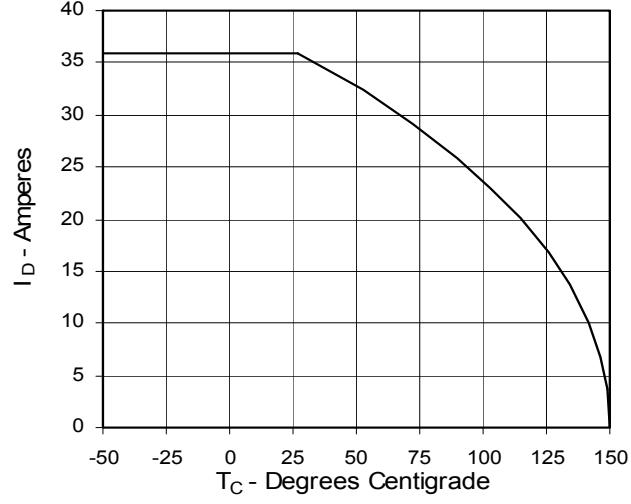
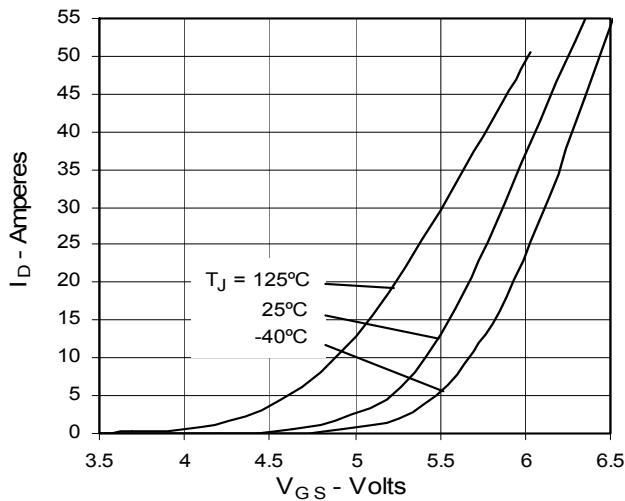
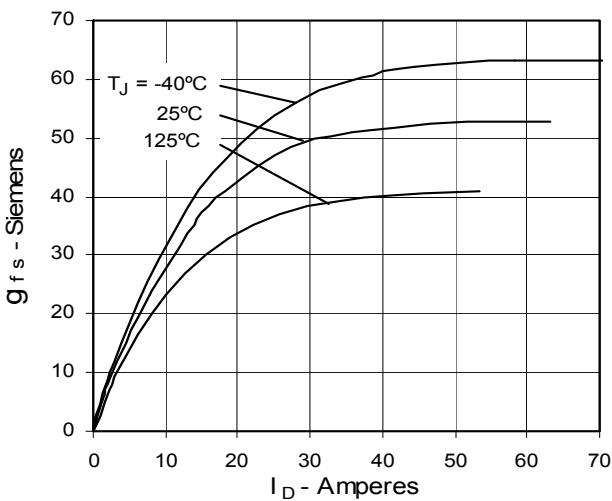
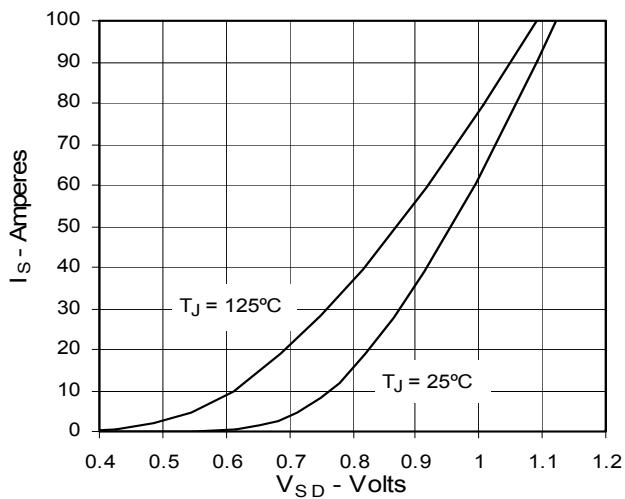
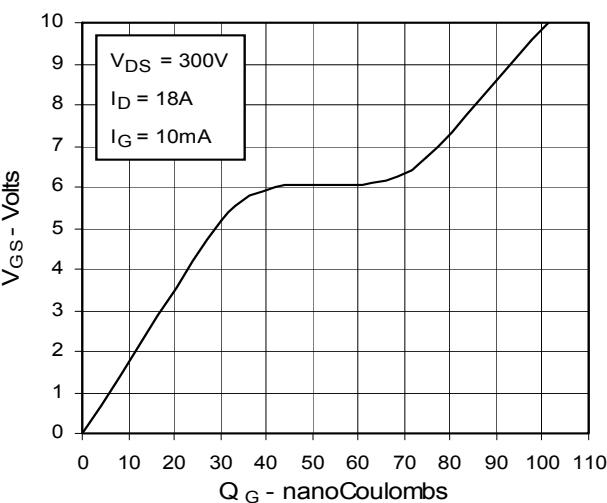
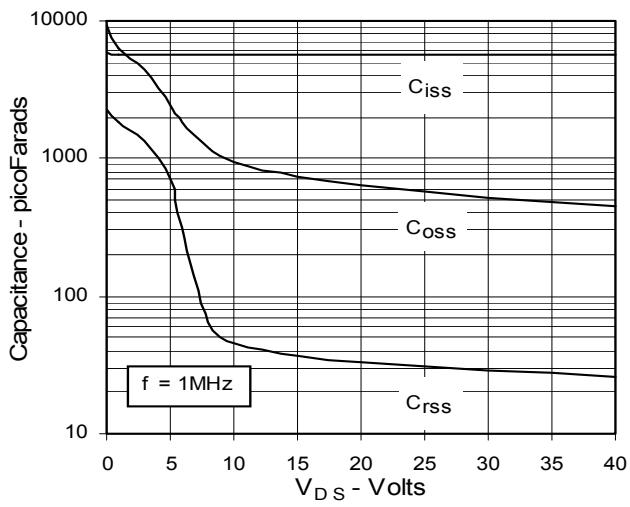
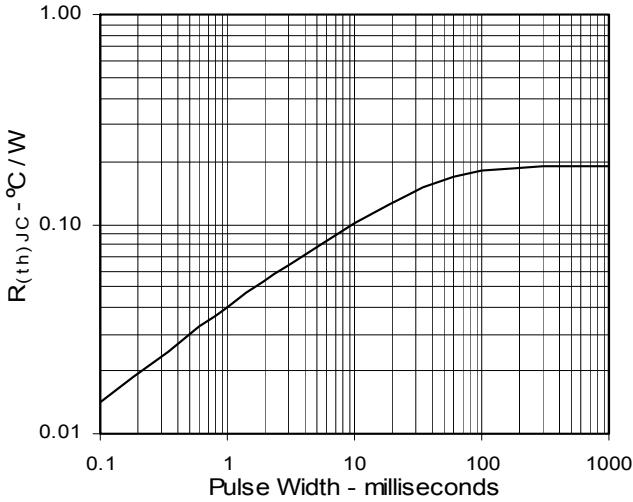


Fig. 7. Input Admittance

Fig. 8. Transconductance

**Fig. 9. Source Current vs.
Source-To-Drain Voltage**

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Resistance


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